DHG60U1200LB

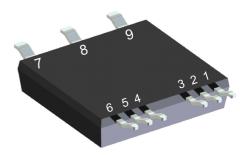
Sonic Fast Recovery Diode

V_{RRM}	=	1200 V		
I _{dav}	=	60 A		
t _{rr}	=	160 ns		

High Performance Fast Recovery Diode Low Loss and Soft Recovery 3~ Rectifier Bridge

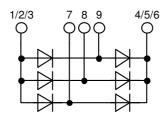
Part number

DHG60U1200LB



Backside: isolated **E**72873

20131211b



Features / Advantages:

- Planar passivated chips
- Very low leakage current
- Very short recovery time
- Improved thermal behaviour
- Very low Irm-values
- Very soft recovery behaviour
- Avalanche voltage rated for reliable operation
- Soft reverse recovery for low EMI/RFI
- Low Irm reduces: - Power dissipation within the diode
- Turn-on loss in the commutating switch

Applications:

- Antiparallel diode for high frequency switching devices
- Antisaturation diode
- Snubber diode
- Free wheeling diode
- Rectifiers in switch mode power supplies (SMPS)
- Uninterruptible power supplies (UPS)

Package: SMPD

- Isolation Voltage: 3000 V~
- Industry convenient outline
- RoHS compliant
- Epoxy meets UL 94V-0
 - Soldering pins for PCB mounting
 - Backside: DCB ceramic
 - Reduced weight
 - Advanced power cycling

Terms Conditions of usage:

The data contained in this product data sheet is exclusively intended for technically trained staff. The user will have to evaluate the suitability of the product for the intended application and the completeness of the product data with respect to his application. The specifications of our components may not be considered as an assurance of component characteristics. The information in the valid application and assertion and applications and principles of the product information in excess of the data given in this product data sheet or which concerns the specific application of your product, please contact the sales office, which is responsible for you.

Due to technical requirements our product may contain dangerous substances. For information on the types in question please contact the sales office, which is responsible for you. Should you intend to use the product in aviation, in health or live endangering or life support applications, please notify. For any such application we urgently recommend to perform joint risk and quality assessments;
the conclusion of quality agreements;

- to establish joint measures of an ongoing product survey, and that we may make delivery dependent on the realization of any such measures.

IXYS reserves the right to change limits, conditions and dimensions.

Data according to IEC 60747and per semiconductor unless otherwise specified

LIXYS

DHG60U1200LB

Fast Diode				Ratings			
Symbol	Definition	Conditions		min.	typ.	max.	Unit
V _{RSM}	max. non-repetitive reverse block	ing voltage	$T_{VJ} = 25^{\circ}C$			1200	V
V _{RRM}	max. repetitive reverse blocking v	oltage	$T_{VJ} = 25^{\circ}C$			1200	V
I _R	reverse current, drain current	$V_{R} = 1200 V$	$T_{VJ} = 25^{\circ}C$			50	μA
		$V_{R} = 1200 V$	$T_{vJ} = 125^{\circ}C$			0.5	mA
V _F	forward voltage drop	I _F = 20 A	$T_{VJ} = 25^{\circ}C$			1.99	V
		I _F = 60 A				1.93	V
		I _F = 20 A	T _{vJ} = 125°C			2.30	V
		I _F = 60 A				3.21	V
	bridge output current	$T_c = 80^{\circ}C$	T _{vJ} = 150°C			60	Α
		rectangular $d = \frac{1}{3}$					
V _{F0}	threshold voltage	threshold voltage				1.35	V
r _F	slope resistance } for power lo	resistance { for power loss calculation only				29	mΩ
R _{thJC}	thermal resistance junction to case					1.2	K/W
R _{thCH}	thermal resistance case to heatsink				0.40		K/W
P _{tot}	total power dissipation		$T_c = 25^{\circ}C$			100	W
	max. forward surge current	t = 10 ms; (50 Hz), sine; $V_{R} = 0 V$	$T_{vJ} = 45^{\circ}C$			200	Α
C	junction capacitance	$V_{R} = 600 V f = 1 MHz$	$T_{vJ} = 25^{\circ}C$		11		pF
I _{RM}	max. reverse recovery current		$T_{VJ} = 25 °C$		19		Α
		$I_{\rm F} = 20 \text{A}; \text{V} = 600 \text{V}$	T _{vJ} = 125 °C		25		А
t _{rr}	reverse recovery time	-d _F /dt = 600 A/μs	$T_{VJ} = 25 ^{\circ}C$		160		ns
	-)	T _{vJ} = 125 °C		280		ns

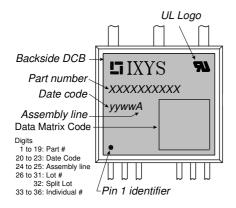
IXYS reserves the right to change limits, conditions and dimensions.

20131211b

LIXYS

DHG60U1200LB

Package SMPD				- I	Ratings			
Symbol	Definition	Conditions		min.	typ.	max.	Unit	
	RMS current	per terminal				100	Α	
T _{vj}	virtual junction temperature			-55		150	°C	
T _{op}	operation temperature			-55		125	°C	
T _{stg}	storage temperature			-55		150	°C	
Weight					8.5		g	
F _c	mounting force with clip			40		130	Ν	
d _{Spp/App}	creepage distance on surface striking distance through air		terminal to terminal	1.6			mm	
d _{Spb/Apb}			terminal to backside	4.0			mm	
	locialion voltage	t = 1 second	50/60 Hz, RMS; IIso∟ ≤ 1 mA	3000			V	
		t = 1 minute		2500			v	



Part description



- H = Sonic Fast Recovery Diode
- G = extreme fast
- 60 = Current Rating [A]
- U = 3~ Rectifier Bridge
- 1200 = Reverse Voltage [V]
- LB = SMPD-B

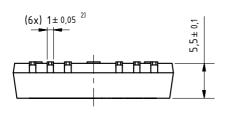
Ordering	Ordering Number	Marking on Product	Delivery Mode	Quantity	Code No.
Standard	DHG60U1200LB	DHG60U1200LB	Blister	45	513421
Alternative	DHG60U1200LB-TRR	DHG60U1200LB	Tape & Reel	200	513414

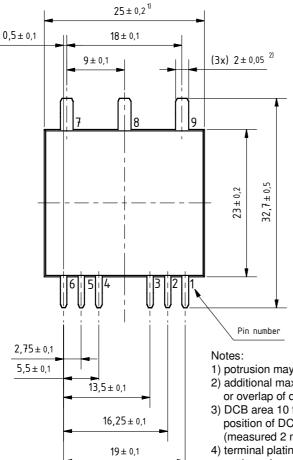
Equivalent Circuits for Simulation			* on die level	T _{vj} = 150 °C
)[Fast Diode		
V _{0 max}	threshold voltage	1.35		V
$\mathbf{R}_{0 \max}$	slope resistance *	27		mΩ

IXYS reserves the right to change limits, conditions and dimensions.

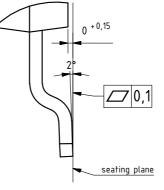
20131211b

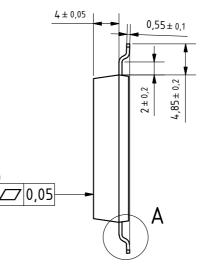
Outlines SMPD





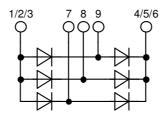
A (8:1)





1) potrusion may add 0.2 mm max. on each side

- 2) additional max. 0.05 mm per side by punching misalignement or overlap of dam bar or bending compression
- DCB area 10 to 50 μm convex; position of DCB area in relation to plastic rim: ±25 μm (measured 2 mm from Cu rim)
- 4) terminal plating: 0.2 1 μm Ni + 10 25 μm Sn (gal v.) cutting edges may be partially free of plating



IXYS reserves the right to change limits, conditions and dimensions.

20131211b

DHG60U1200LB

Fast Diode

